

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	60	mA
	Peak forward current (1us, pulse)	I _{FP}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P _D	100	mW
	Derating factor (above T _a = 100°C)		2.9	mW/°C
Output	Power dissipation	P _C	150	mW
	Derating factor (above T _a = 100°C)		5.8	mW/°C
	Collector current	I _C	50	mA
	Collector-Emitter voltage	V _{CEO}	80	V
	Emitter-Collector voltage	V _{ECO}	7	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V _{ISO}	5000	V rms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature*2		T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V_F	-	1.2	1.4	V	$I_F = 20\text{mA}$
Reverse Current	I_R	-	-	10	μA	$V_R = 4\text{V}$
Input capacitance	C_{in}	-	30	250	pF	$V = 0, f = 1\text{kHz}$

Output

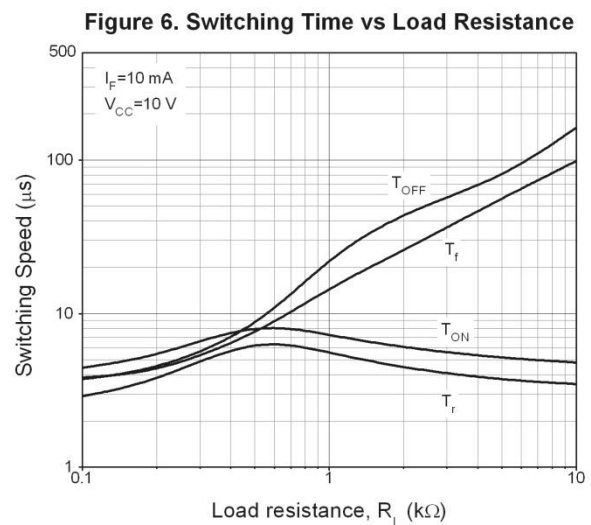
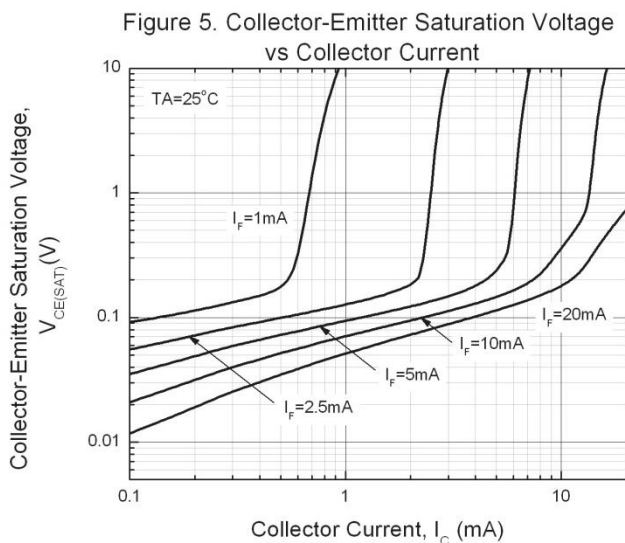
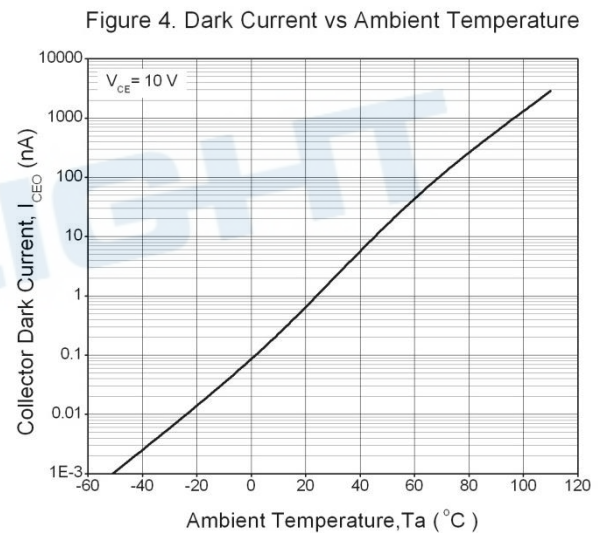
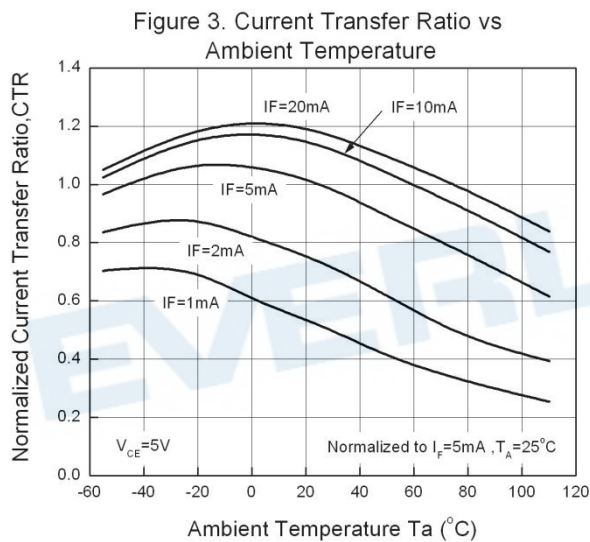
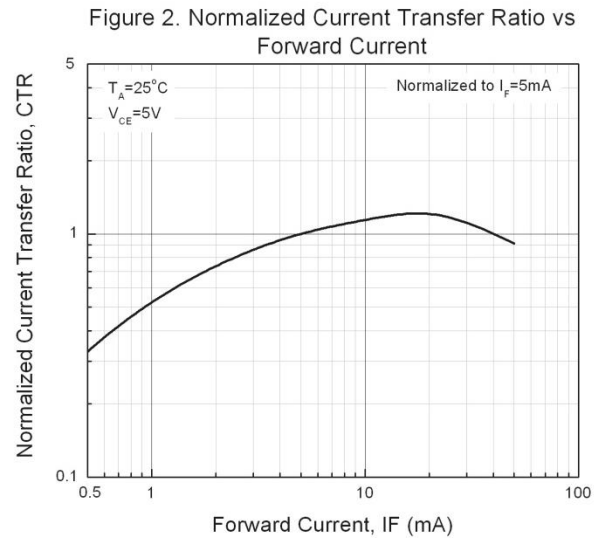
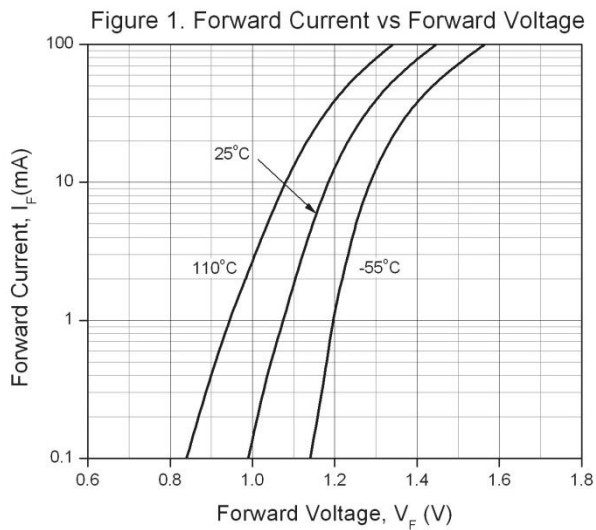
Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I_{CEO}	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	BV_{CEO}	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	BV_{ECO}	7	-	-	V	$I_E = 0.1\text{mA}$

Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL817	50	-	600	%	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$
	EL817A	80	-	160		
	EL817B	130	-	260		
	EL817C	200	-	400		
	EL817D	300	-	600		
	EL817X	100	-	200		
	EL817Y	150	-	300		
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_F = 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	R_{IO}	5×10^{10}	-	-	Ω	$V_{IO} = 500\text{Vdc}, 40 \sim 60\% \text{ R.H.}$
Floating capacitance	C_{IO}	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	f_c	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Rise time	t_r	-	6	18	μs	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	t_f	-	8	18	μs	

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves



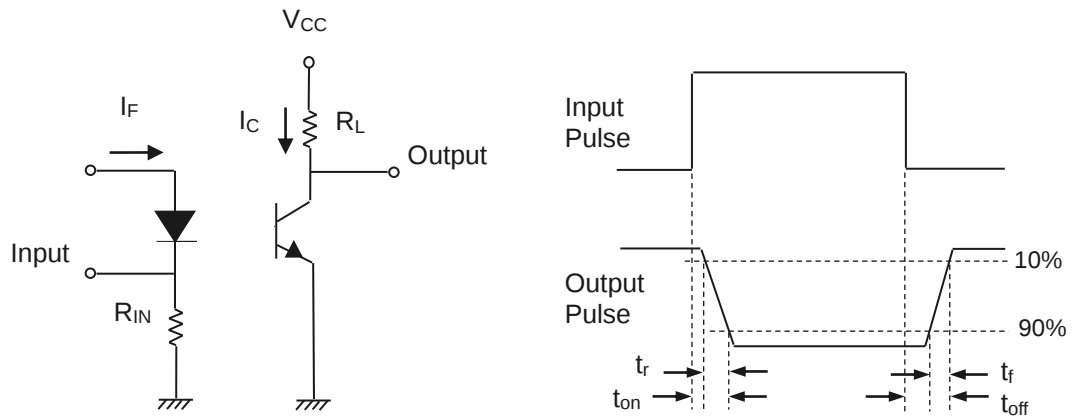


Figure 7. Switching Time Test Circuit & Waveforms

Order Information

Part Number

EL817X(Y)(Z)-FVG

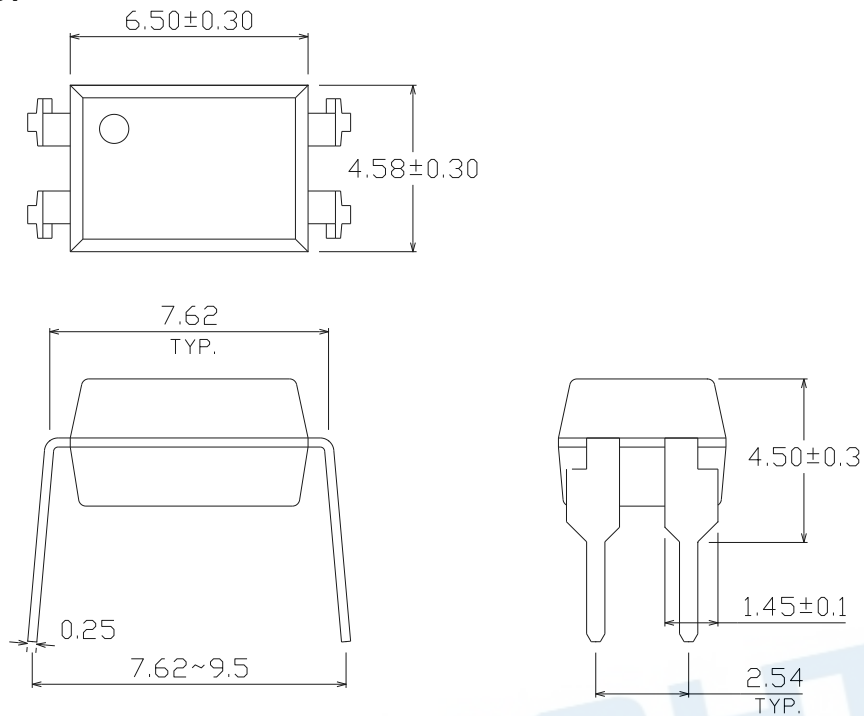
Note

- X = Lead form option (S1, S2, M or none)
Y = CTR Rank (A, B, C, D, X, Y or none)
Z = Tape and reel option (TU, TD or none)
F = Lead frame option (F: Iron, None: copper)
V = VDE safety (optional)
G = Halogens free

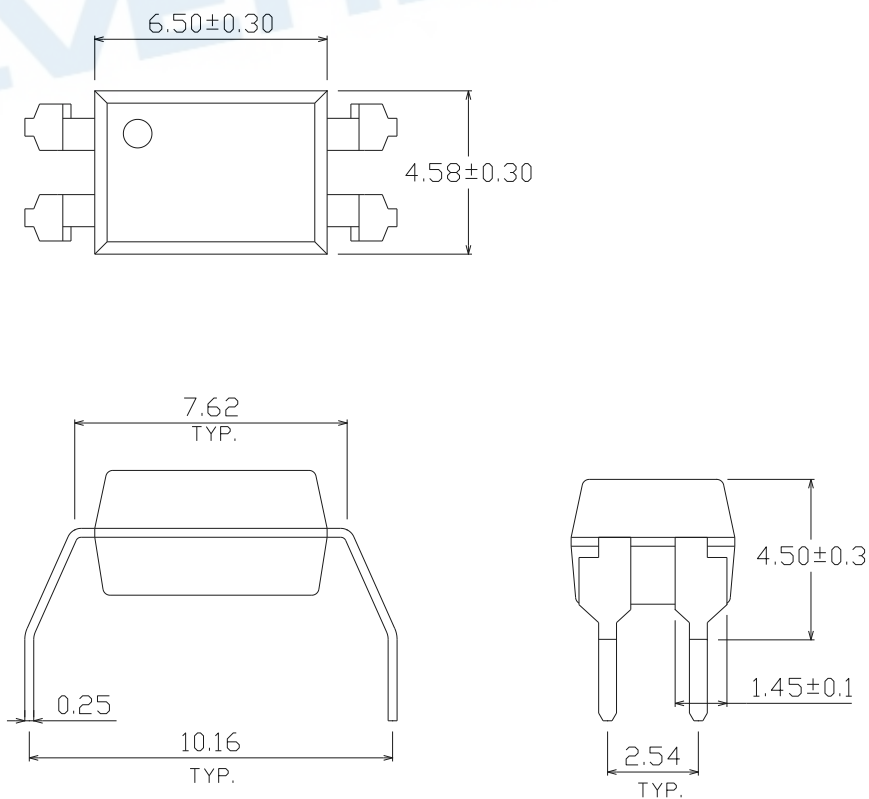
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

Package Dimension (Dimensions in mm)

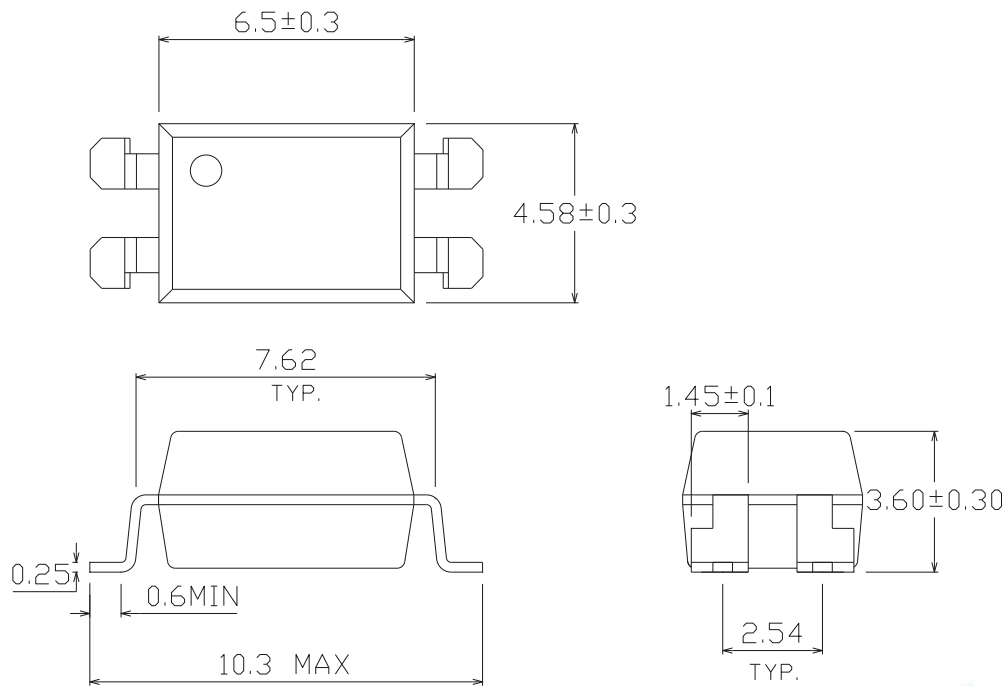
Standard DIP Type



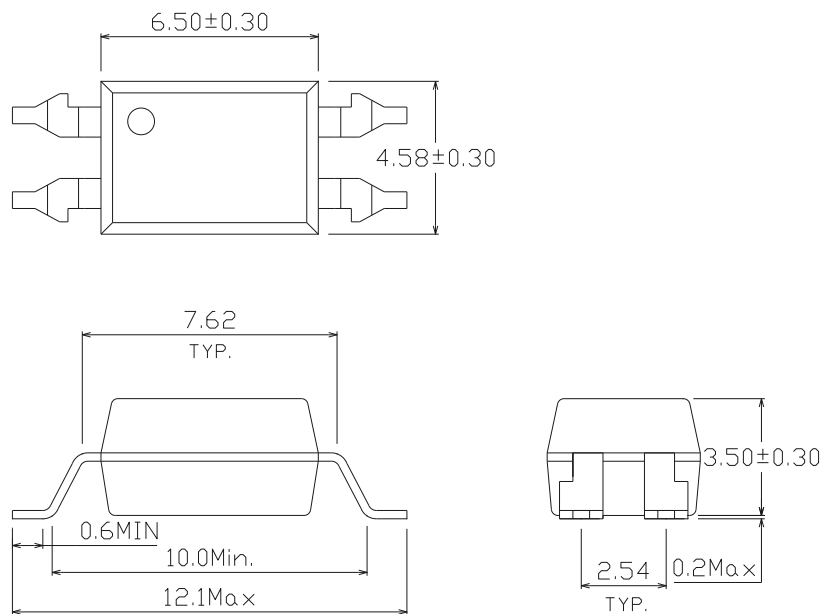
Option M Type



Option S1 Type

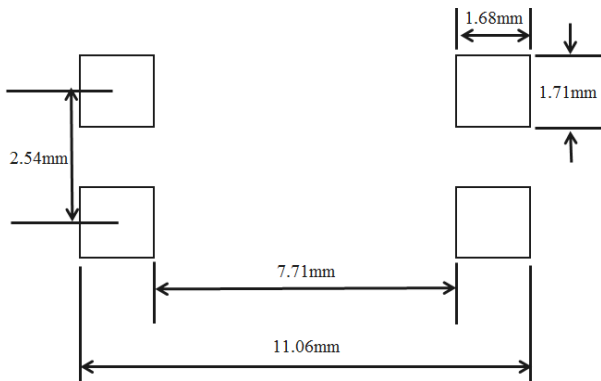


Option S2 Type

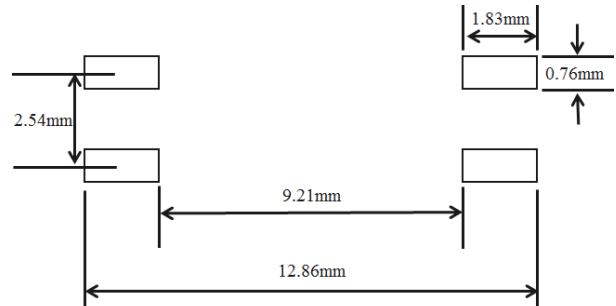


Recommended pad layout for surface mount leadform

For S1 option



For S2 option



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

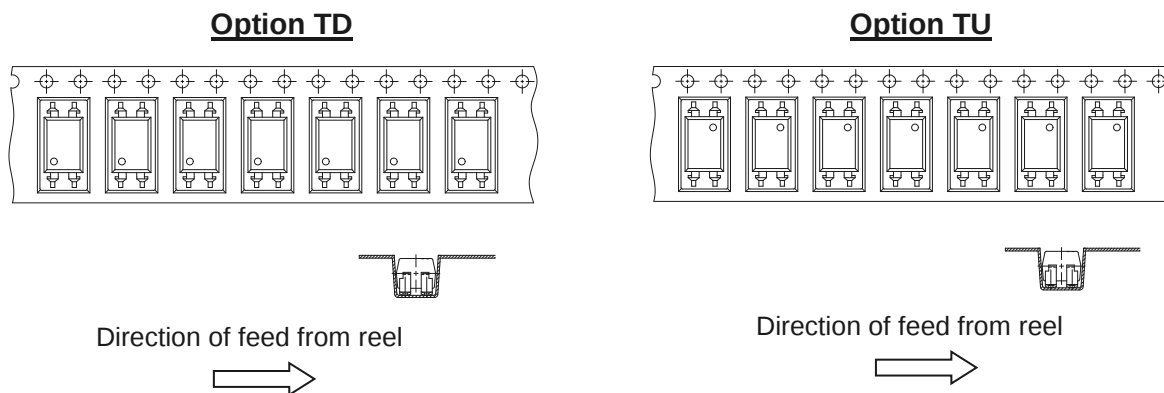
Device Marking



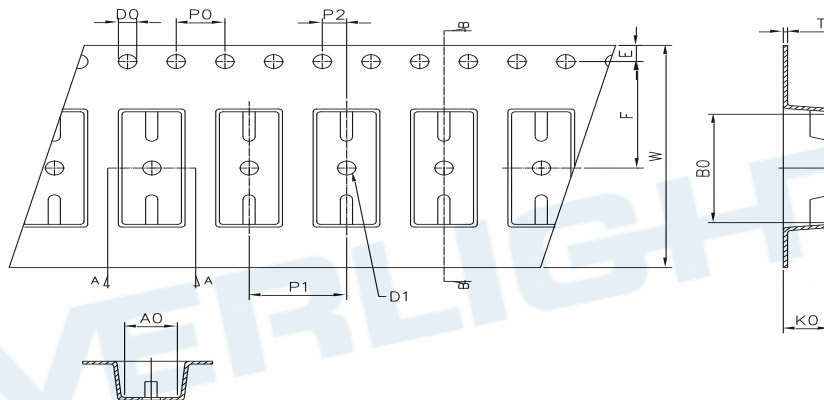
Notes

EL denotes EVERLIGHT
817 denotes Device Number
G denotes Green part
R denotes CTR Rank (A, B, C, D, X, Y or none)
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)

Tape & Reel Packing Specifications



Tape dimensions

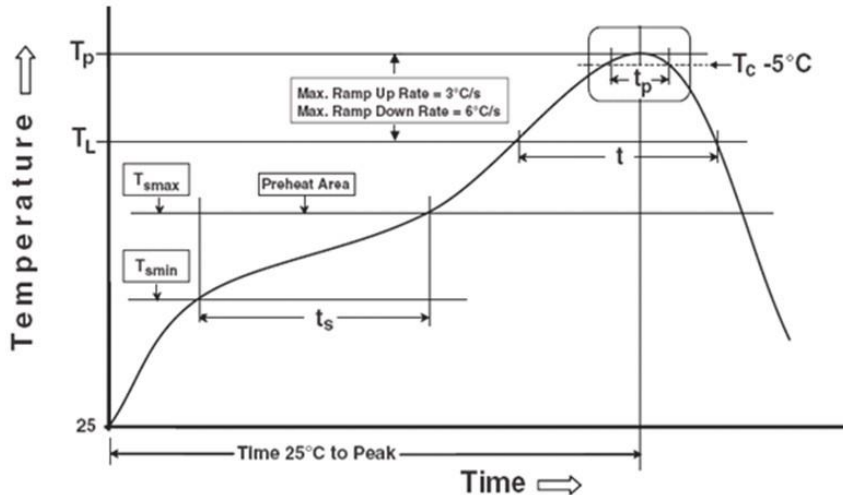


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ C$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

DISCLAIMER

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